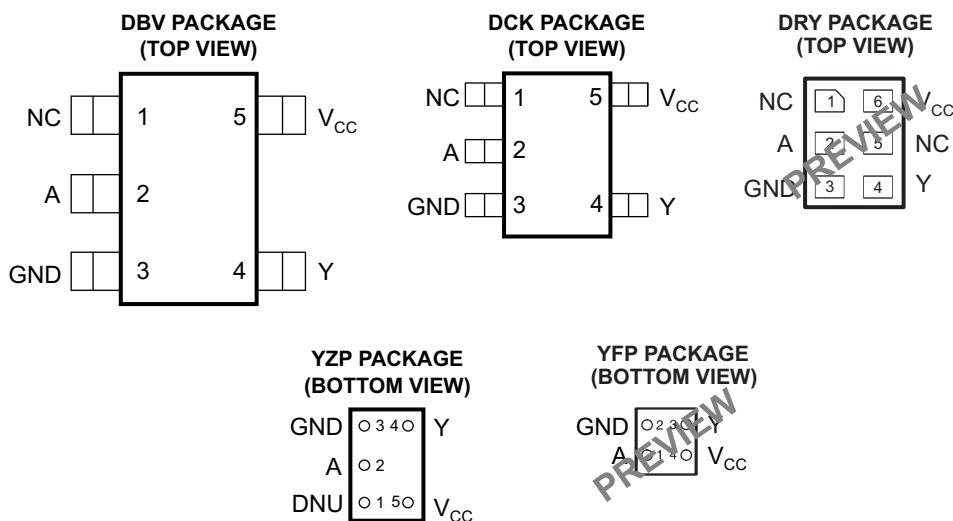


FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Low Static-Power Consumption ($I_{CC} = 0.9 \mu\text{A}$ Maximum)
- Low Dynamic-Power Consumption ($C_{pd} = 1 \text{ pF}$ Typical at 3.3 V)
- Low Input Capacitance ($C_i = 1.5 \text{ pF}$ Typical)
- Low Noise – Overshoot and Undershoot <math><10\%</math> of V_{CC}
- I_{off} Supports Partial-Power-Down Mode Operation
- Input Hysteresis Allows Slow Input Transition and Better Switching Noise Immunity at the Input ($V_{hys} = 250 \text{ mV}$ Typ at 3.3 V)
- Wide Operating V_{CC} Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- $t_{pd} = 3.3 \text{ ns}$ Maximum at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- ESD Protection Exceeds $\pm 5000 \text{ V}$ With Human-Body Model



NC – No internal connection

DNU – Do not use

See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The AUP family is TI's premier solution to the industry's low power needs in battery-powered portable applications. This family ensures a very low static and dynamic power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity (see Figure 1 and Figure 2).

The output of this single buffer/driver is open drain, and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoFree is a trademark of Texas Instruments.

SN74AUP1G07

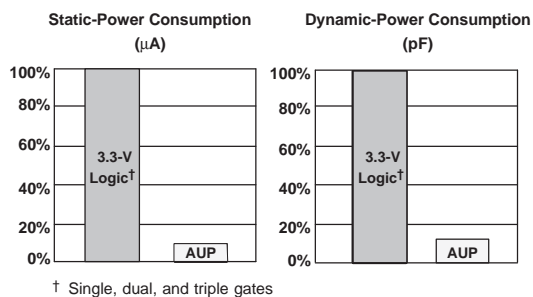
LOW-POWER SINGLE BUFFER/DRIVER

WITH OPEN-DRAIN OUTPUTS

SCES591C—JULY 2004—REVISED OCTOBER 2007

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



† Single, dual, and triple gates

Figure 1. AUP – The Lowest-Power Family



† AUP1G08 data at $C_L = 15$ pF

Figure 2. Excellent Signal Integrity

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽³⁾
-40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YFP	Reel of 3000	SN74AUP1G07YFPR	PREVIEW
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74AUP1G07YZPR	___HV_
	SON – DRY	Reel of 5000	SN74AUP1G07DRYR	PREVIEW
	SOT (SOT-23) – DBV	Reel of 3000	SN74AUP1G07DBVR	H07_
		Reel of 250	SN74AUP1G07DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74AUP1G07DCKR	HV_
Reel of 250		SN74AUP1G07DCKT		

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

(3) DBV/DCK/DRY: The actual top-side marking has one additional character that designates the assembly/test site.
YFP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

FUNCTION TABLE

INPUT A	OUTPUT Y
H	H
L	L

LOGIC DIAGRAM (POSITIVE LOGIC) (DBV, DCK, DRY, and YZP Packages)



(YFP Package)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	–0.5	4.6	V
V _I	Input voltage range ⁽²⁾	–0.5	4.6	V
V _O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	–0.5	4.6	V
V _O	Voltage range applied to any output in the high or low state ⁽²⁾	–0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0	–50	mA
I _{OK}	Output clamp current	V _O < 0	–50	mA
I _O	Continuous output current		±20	mA
	Continuous current through V _{CC} or GND		±50	mA
θ _{JA}	Package thermal impedance ⁽³⁾	DBV package	206	°C/W
		DCK package	252	
		DRY package	234	
		YFP/YZP package	132	
T _{stg}	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	0.8	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 0.8 V	V _{CC}	V
		V _{CC} = 1.1 V to 1.95 V	0.65 × V _{CC}	
		V _{CC} = 2.3 V to 2.7 V	1.6	
		V _{CC} = 3 V to 3.6 V	2	
V _{IL}	Low-level input voltage	V _{CC} = 0.8 V	0	V
		V _{CC} = 1.1 V to 1.95 V	0.35 × V _{CC}	
		V _{CC} = 2.3 V to 2.7 V	0.7	
		V _{CC} = 3 V to 3.6 V	0.9	
V _I	Input voltage	0	3.6	V
V _O	Output voltage	0	3.6	V
I _{OL}	Low-level output current	V _{CC} = 0.8 V	20	mA
		V _{CC} = 1.1 V	1.1	
		V _{CC} = 1.4 V	1.7	
		V _{CC} = 1.65 V	1.9	
		V _{CC} = 2.3 V	3.1	
		V _{CC} = 3 V	4	
Δt/Δv	Input transition rise or fall rate	V _{CC} = 0.8 V to 3.6 V	200	ns/V
T _A	Operating free-air temperature	–40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74AUP1G07

LOW-POWER SINGLE BUFFER/DRIVER WITH OPEN-DRAIN OUTPUTS

SCES591C—JULY 2004—REVISED OCTOBER 2007

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{OL}	I _{OL} = 20 μA	0.8 V to 3.6 V			0.1		0.1	V
	I _{OL} = 1.1 mA	1.1 V			0.3 × V _{CC}		0.3 × V _{CC}	
	I _{OL} = 1.7 mA	1.4 V			0.31		0.37	
	I _{OL} = 1.9 mA	1.65 V			0.31		0.35	
	I _{OL} = 2.3 mA	2.3 V			0.31		0.33	
	I _{OL} = 3.1 mA				0.44		0.45	
	I _{OL} = 2.7 mA	3 V			0.31		0.33	
	I _{OL} = 4 mA				0.44		0.45	
I _I	A input	V _I = GND to 3.6 V			0.1		0.5	μA
I _{off}		V _I or V _O = 0 V to 3.6 V			0.2		0.6	μA
ΔI _{off}		V _I or V _O = 0 V to 3.6 V			0.2		0.6	μA
I _{CC}		V _I = GND or V _{CC} to 3.6 V, I _O = 0			0.5		0.9	μA
ΔI _{CC}		V _I = V _{CC} - 0.6 V, I _O = 0			40		50	μA
C _i	V _I = V _{CC} or GND	0 V			1.5			pF
		3.6 V			1.7			
C _O	V _O = GND	0 V			1.7			pF

Switching Characteristics

over recommended operating free-air temperature range, C_L = 5 pF (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A	Y	0.8 V			12.2			ns
			1.2 V ± 0.1 V	3.4	5.1	7.5	1.5	14.7	
			1.5 V ± 0.1 V	2.3	3.6	5.1	1.3	8.3	
			1.8 V ± 0.15 V	2.4	3.1	4	1	6.3	
			2.5 V ± 0.2 V	1.5	2.1	2.9	0.9	4.1	
			3.3 V ± 0.3 V	1.8	2.2	2.8	1.1	3.3	

Switching Characteristics

over recommended operating free-air temperature range, C_L = 10 pF (unless otherwise noted) (see Figure 3 and Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			T _A = -40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t _{pd}	A	Y	0.8 V			15			ns
			1.2 V ± 0.1 V	4	6.2	9	2.4	16.2	
			1.5 V ± 0.1 V	3.1	4.4	6.1	2	9.4	
			1.8 V ± 0.15 V	3.3	3.9	4.8	1.6	7.1	
			2.5 V ± 0.2 V	2.1	2.8	3.5	1.3	4.8	
			3.3 V ± 0.3 V	2.3	3	4	1.4	4.5	

Switching Characteristics

 over recommended operating free-air temperature range, $C_L = 15$ pF (unless otherwise noted) (see [Figure 3](#) and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8 V	18.2					ns
			$1.2\text{ V} \pm 0.1\text{ V}$	4.9	7.3	10.4	3.2	17.6	
			$1.5\text{ V} \pm 0.1\text{ V}$	3.8	5.2	6.8	2.6	10.2	
			$1.8\text{ V} \pm 0.15\text{ V}$	3.4	4.8	6.7	2.2	7.9	
			$2.5\text{ V} \pm 0.2\text{ V}$	2.4	3.4	4.5	1.9	5.3	
			$3.3\text{ V} \pm 0.3\text{ V}$	2.2	3.7	5.4	1.8	6.1	

Switching Characteristics

 over recommended operating free-air temperature range, $C_L = 30$ pF (unless otherwise noted) (see [Figure 3](#) and [Figure 4](#))

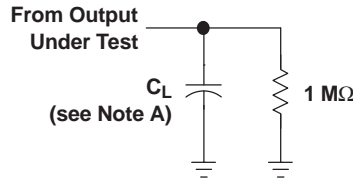
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8 V	26.5					ns
			$1.2\text{ V} \pm 0.1\text{ V}$	8.1	10.7	14.4	4.5	21.9	
			$1.5\text{ V} \pm 0.1\text{ V}$	6.5	7.7	9.4	3.8	13	
			$1.8\text{ V} \pm 0.15\text{ V}$	5.8	7.5	9.7	3.2	11	
			$2.5\text{ V} \pm 0.2\text{ V}$	4.5	5.4	6.7	3	7.1	
			$3.3\text{ V} \pm 0.3\text{ V}$	3.9	6.3	9.7	2.8	10.4	

Operating Characteristics

 $T_A = 25^\circ\text{C}$

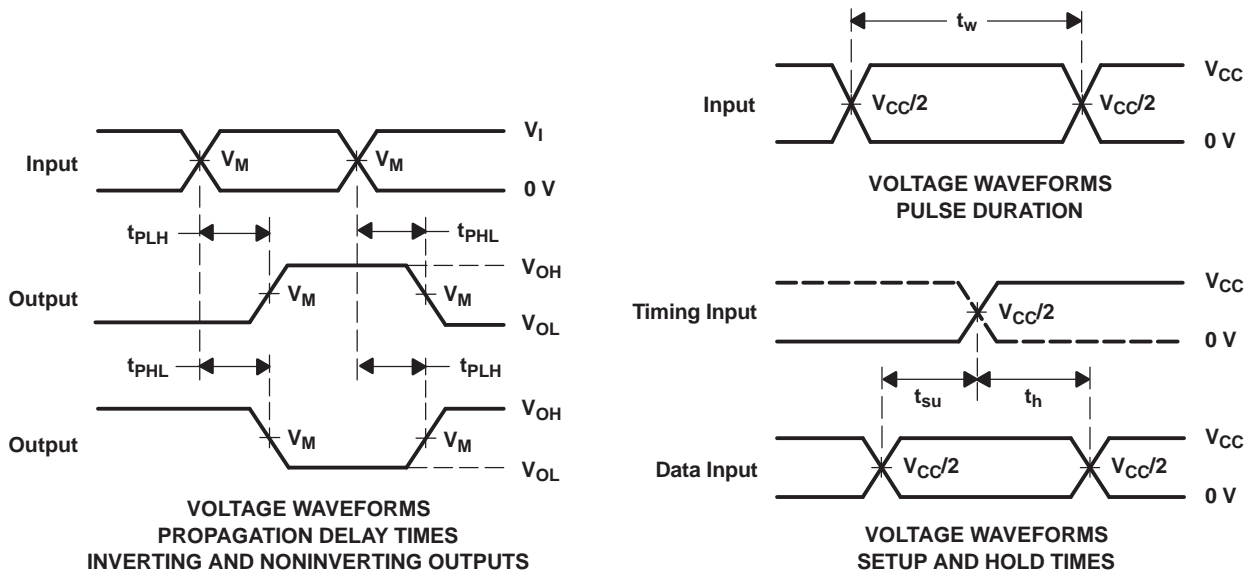
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$f = 10\text{ MHz}$	0.8 V	1	pF
			$1.2\text{ V} \pm 0.1\text{ V}$	1	
			$1.5\text{ V} \pm 0.1\text{ V}$	1	
			$1.8\text{ V} \pm 0.15\text{ V}$	1	
			$2.5\text{ V} \pm 0.2\text{ V}$	1	
			$3.3\text{ V} \pm 0.3\text{ V}$	1	

PARAMETER MEASUREMENT INFORMATION
(Propagation Delays, Setup and Hold Times, and Pulse Duration)



LOAD CIRCUIT

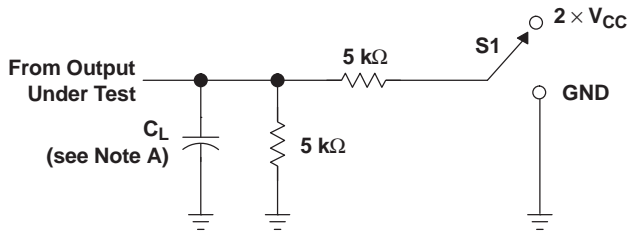
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



- NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r/t_f = 3$ ns.
C. The outputs are measured one at a time, with one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd} .
E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

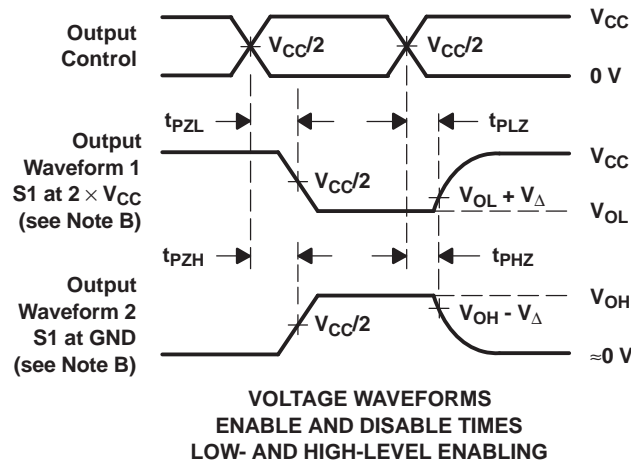
PARAMETER MEASUREMENT INFORMATION
(Enable and Disable Times)



TEST	S1
t_{PLZ}/t_{PZL}	2 \times V_{CC}
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_{Δ}	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r/t_f = 3 \text{ ns}$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AUP1G07DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DRLR	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07DRLRG4	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G07YZPR	ACTIVE	WCSP	YZP	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

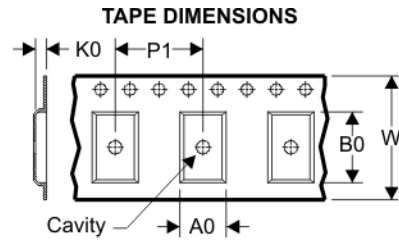
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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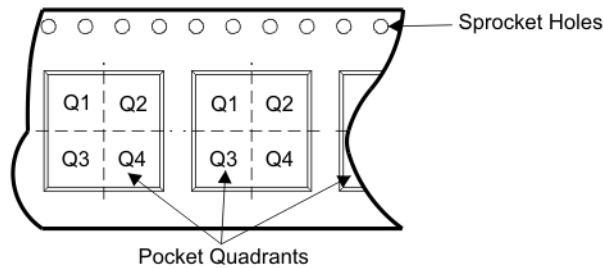
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL BOX INFORMATION



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G07DBVR	DBV	5	SITE 35	180	9	3.23	3.17	1.37	4	8	Q3
SN74AUP1G07DBVT	DBV	5	SITE 35	180	9	3.23	3.17	1.37	4	8	Q3
SN74AUP1G07DCKR	DCK	5	SITE 35	180	9	2.24	2.34	1.22	4	8	Q3
SN74AUP1G07DCKT	DCK	5	SITE 35	180	9	2.24	2.34	1.22	4	8	Q3
SN74AUP1G07DRLR	DRL	5	SITE 35	180	9	1.78	1.78	0.69	4	8	Q3
SN74AUP1G07YZPR	YZP	5	SITE 12	180	8	1.02	1.52	0.66	4	8	Q1

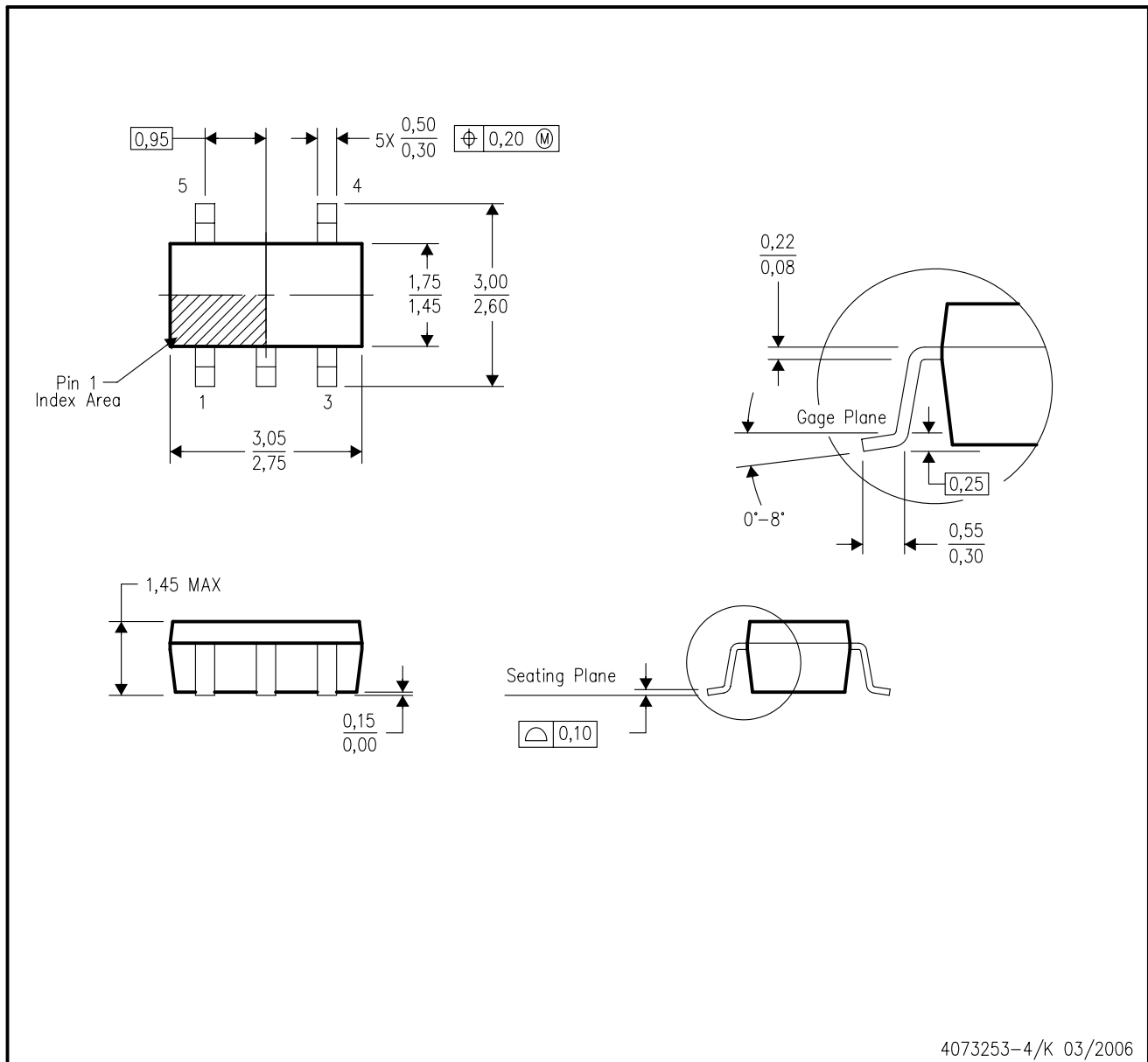
TAPE AND REEL BOX DIMENSIONS



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G07DBVR	DBV	5	SITE 35	202.0	201.0	28.0
SN74AUP1G07DBVT	DBV	5	SITE 35	202.0	201.0	28.0
SN74AUP1G07DCKR	DCK	5	SITE 35	202.0	201.0	28.0
SN74AUP1G07DCKT	DCK	5	SITE 35	202.0	201.0	28.0
SN74AUP1G07DRLR	DRL	5	SITE 35	202.0	201.0	28.0
SN74AUP1G07YZPR	YZP	5	SITE 12	220.0	220.0	0.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



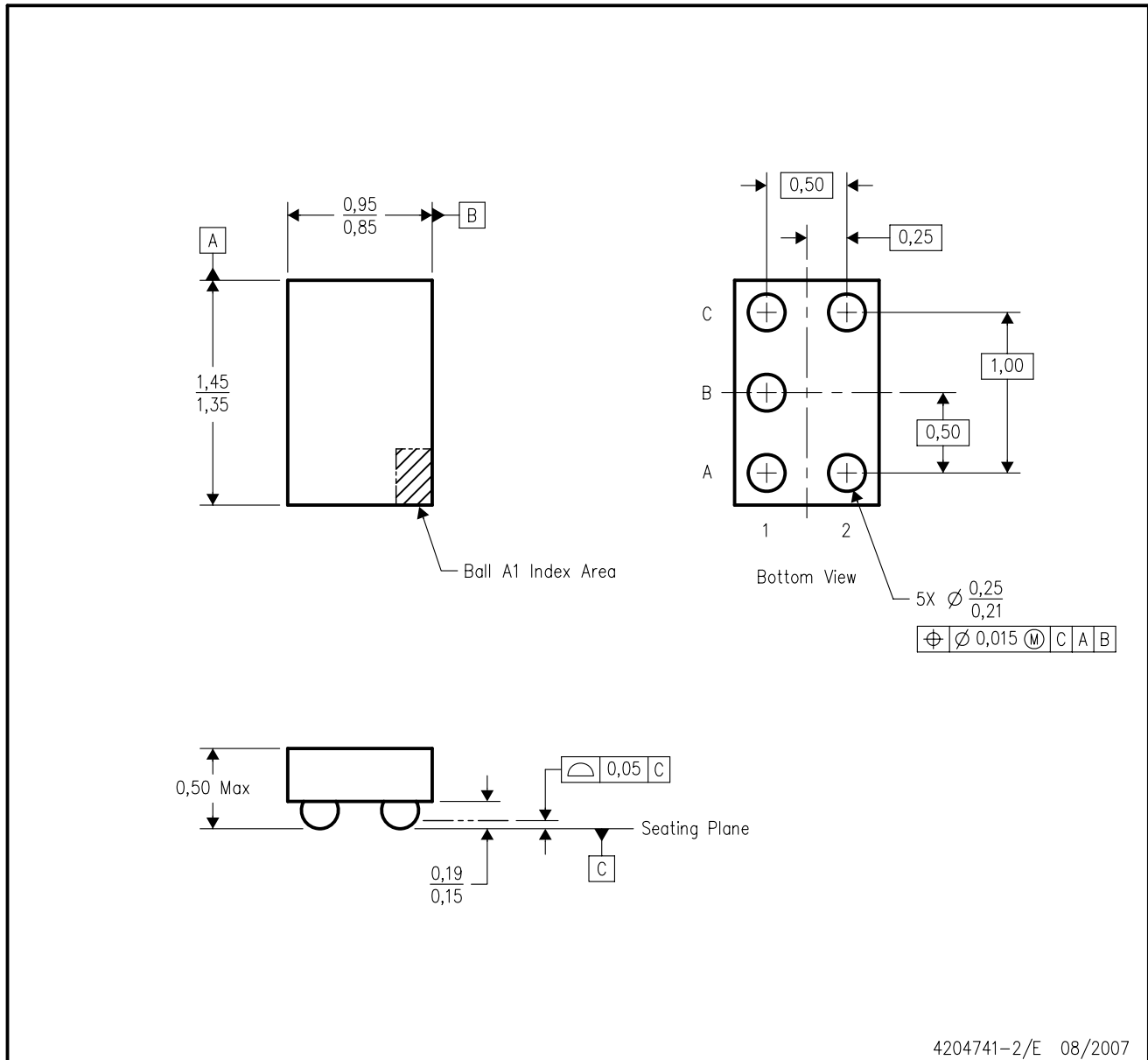
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
 - D. JEDEC package registration is pending.

YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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